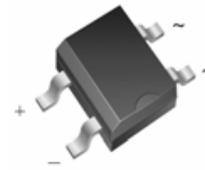


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junctions
- High surge overload rating: 35A peak
- Saves space on printed circuit boards
- High temperature soldering guaranteed: 260 °C/10 seconds.

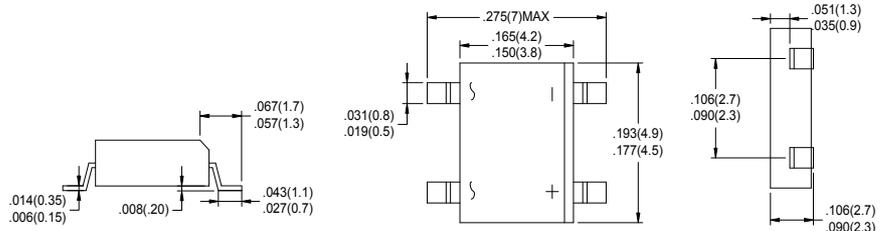
MB2S---MB10S



CASE:MB-S

Mechanical Data

- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Polarity: Polarity Symbols Marked on Body



Unit: mm

Maximum Ratings and Electrical Characteristics (T =25°C unless otherwise noted)

Parameter	Symbols	MB2S	MB4S	MB6S	MB8S	MB10S	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	Volts
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	Volts
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	Volts
Maximum average forward output rectified current (see Fig.1) on glass-epoxy P.C.B. on aluminum substrate	I _{F(AV)}			0.5 (1) 0.8 (2)			Amp
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}			30.0			Amps
Rating for fusing (t < 8.3ms)	I ² t			5.0			A ² sec
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F			1.0			Volt
Maximum DC reverse current at T _A = 25°C rated DC blocking voltage per leg T _A = 125°C	I _R			5.0 500			uA
Typical thermal resistance per leg	R _{JA} R _{JA} R _{JL}			85 (1) 70 (2) 20 (1)			°C/W
Typical junction capacitance per leg at 4.0V, 1.0MHz	C _J			13			pF
Operating junction and storage temperature range	T _J , T _{STG}			-55 to +150			°C

Notes: 1. On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3mm) pads
2. On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad

MB2S---MB10S Typical Characteristics

